



# Virtex-4 and Virtex-5 FPGA Flip Chip BGA Package Material BT-to-ABF Conversion

XCN11004 (v1.1) May 2, 2011

Product Change Notice

## Overview

The purpose of this notification is to communicate an addition of a new supply source for Virtex®-4 and Virtex®-5 FPGA flip chip package build up layers.

## Description

Due to the recent earthquake in Japan, there is a worldwide shortage of Bismaleimide-Triazine (BT) resin material used in the package core and build up layers of flip chip packages. To ensure supply continuity, the package build up layers have been qualified with ABF material. The ABF materials set is already qualified and in production for other Virtex®-II Pro FPGA, Virtex-4 FPGA and Virtex-5 FPGA products per [XCN09013](#) and [XCN10013](#). There are no changes in the form, fit or function of the package.

## Products Affected

This change affects all speed, package, and temperature variations of the commercial (C) and industrial (I) grade devices. Automotive, and Aerospace and Defense devices are not affected by this change. Affected product families are included in the following table(s):

Table 1: Product Changes

Xilinx Product	Package
XC5VSX240T	FF(G)1738
XC5VLX330T	FF(G)1738
XC5VLX330	FF(G)1760
XC5VLX220T	FF(G)1738
XC5VLX220	FF(G)1760
XC5VLX155T	FF(G)1738
XC5VLX155	FF(G)1760
XC5VLX110T	FF(G)1738
XC5VLX110	FF(G)1760
XC4VSX35	FF(G)668
XC4VLX60	FF(G)668
XC4VLX25	FF(G)668

## Key Dates and Ordering Information

Xilinx will begin to cross-ship production using BT and ABF package materials on or after 30 days of April 18, 2011.

## Qualification Data

This ABF package material is already qualified for Virtex-II Pro FPGA, Virtex-4 FPGA and Virtex-5 FPGA devices and is running in production with selected devices today. Qualification data & device reliability report for Virtex-4 FPGA and Virtex-5 FPGA devices is available in [UG116](#). The extended qualification data related to this PCN is available in [RPT141](#) located in 'Additional Document' section below.

## Response

**Note:** in accordance with JESD46-C, this change is deemed accepted by the customer if no acknowledgement is received within 30 days from this notice.

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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## Additional Documentation

Qualification Report (RPT141)  
<https://secure.xilinx.com/webreg/clickthrough.do?cid=140202>

Device Reliability Report (UG116):  
[http://www.xilinx.com/support/documentation/user\\_guides/ug116.pdf](http://www.xilinx.com/support/documentation/user_guides/ug116.pdf)

## Revision History

The following table shows the revision history for this document.

Date	Version	Revision
04/18/2011	1.0	Initial release.
05/02/2011	1.1	Remove the Xilinx part "XC5VLX30-FF(G)324" from <a href="#">Table 1</a> .

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